GaAs Nanowire Growth on Polycrystalline Silicon Thin Films Using Selective-area MOVPE

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ABSTRACT

The growth mechanism of GaAs nanowires (NWs) grown on polycrystalline silicon (poly-Si) thin films using selective-area metalorganic vapor-phase epitaxy was investigated. Wire structures were selectively grown in the mask openings on a poly-Si substrate. The appearance ratio of wire structures strongly depended on the growth conditions and deposition temperature
of the poly-Si substrate. Evaluation of the grown shapes and growth characteristics revealed that GaAs NWs grown on a poly-Si substrate have the same growth mechanism as conventional GaAs NWs grown on a single-crystalline GaAs or Si substrate. Experiments showed that the wire structure yield can be improved by increasing the Si grain size and/or increasing the Si deposition temperature. The growth model proposed for understanding NW growth on poly-Si is based on the mask opening size, the Si grain size, and the growth conditions. The ability to control the growth mode is promising for the formation of nanowires with complex structures on poly-Si thin layers.

1. Introduction

Semiconductor nanowires (NWs), which have diameters on the nanometer scale, can be produced by using a crystal growth technique and can potentially be fabricated with various kinds of structures such as radial (core-shell) [1–3], axial [4,5], hetero, and quantum dot [6–8]. Such NW structures could be used in nanoscale devices including light-emitting diodes (LEDs) [9–11], lasers [12], photodetectors [13], field effect transistors [1,9], and photovoltaic devices [14]. Core-shell NWs are a promising candidate for high-efficiency LEDs because these types of heterostructures have large surface areas with diameters on the nanometer scale and can potentially have a junction area more than ten times that of conventional planar LEDs.
We have grown III–V compound semiconductor NWs by using selective-area metal organic vapor-phase epitaxy (SA-MOVPE) [1–3,5,11,14–19]. With this method, III–V NWs with precise positioning and vertical alignment have been grown on not only III–V substrates but also Si ones regardless of any mismatch in the lattice constant [15,16]. The elastic relaxation of a strained layer occurs near the interface because the crystal growth area is limited to only the small openings in an amorphous mask. This is greatly advantageous for selecting both NW and substrate materials. For example, NWs can be formed on lattice mismatched substrates such as GaAs/Si [16] and InAs/Si [15]. We previously grew AlGaAs/GaAs core-multi-shell NW LEDs on Si [11].

Scarce resources such as Ga and In must be used efficiently, and conventional LEDs contain a large amount of such high-cost rare materials in their substrates. In contrast, NW LEDs can be grown on a low-cost Si substrate. Further progress in developing low-cost LEDs is expected to follow the emergence of glass-based poly-crystalline silicon (poly-Si) thin-film substrates for NW optical devices owing to their lower production cost and greater scalability than conventional LED structures formed on compound semiconductor substrates. Poly-Si substrates are formed using mature processes that have been used to form glass-based flat-panel displays, and they have good compatibility with high-volume manufacturing processes.

NWs have been synthesized by vapor–liquid–solid growth on a non-single crystalline surface
such as InP nano-needles on microcrystalline silicon surfaces [20,21], Si NWs have been grown on amorphous Si substrates by host-mediated catalyst growth [22], and InP NWs have been grown on oxidized silicon substrates by laser-assisted catalytic growth [23]. However, there have been no detailed reports on the growth mechanism of NWs grown on microcrystalline or non-crystalline surfaces from the crystal growth point of view. To be able to grow a nanowire device on poly-Si we need to understand the mechanism of selective area growth of nanowires on a polycrystalline surface. We can then fabricate an appropriate NW structure for the device application, especially LEDs. Here, we demonstrate the growth of GaAs NWs on poly-Si by SA-MOVPE and clarify the correlation between the growth morphology, the growth conditions, and the crystallinity of the underlying poly-Si.

2. Experimental procedure

A 50-nm-thick poly-Si thin film was used as the substrate. It was deposited on a 300-nm-thick SiO$_2$-coated Si (001) wafer using RF sputtering. The SiO$_2$-coated Si (001) wafer corresponds to an equivalent glass substrate. The SiO$_2$/Si wafer temperature ($T_s$) during poly-Si deposition ranged from room temperature (RT) to 600°C. Next, a 20-nm-thick SiO$_2$ layer was formed on the poly-Si substrate as a mask by thermal oxidation at 900°C. It was then partially removed using electron beam lithography and wet chemical etching to form periodic mask openings as a template for selective-area growth. A grown substrate is schematically illustrated in Fig. 1 (a).
The diameter, \(d_0\), of the openings varied from 60 to 200 nm, and the opening pitch, \(a\), of the mask was 500 nm. Finally, these substrates were degreased in organic solvents in an ultrasonic bath and slightly etched with buffered HF (BHF) solution to remove the native oxide that had formed on the openings during processing.

Next, GaAs growth was carried out using a horizontal low-pressure MOVPE system. The total flow rate of the gases was maintained at 5.75 standard liters per minute. The working pressure was 0.1 atm, and the source materials were trimethylgallium (TMG) and arsine (AsH\(_3\)). The growth time was 30 minutes. The partial pressures of the TMG and AsH\(_3\) were \(2.5 \times 10^{-6}\) and \(5.0 \times 10^{-4}\) atm, respectively, which are typical conditions for growing GaAs nanowires on Si (111) substrates [16]. Prior to growth, thermal cleaning in an H\(_2\) ambient was carried out at 900°C to remove the native oxide on the mask openings. The growth temperature (\(T_G\)) was 650, 700, or 760°C. The grown structures were characterized by scanning electron microscopy (SEM) and transmission electron microscopy (TEM).

3. Results and discussion

3.1 Growth morphologies of GaAs on poly-Si thin films

For the selective-area MOVPE, we used partially opened amorphous thin films as mask templates. We previously grew GaAs NWs on GaAs (111)B [17,19] and Si (111) [16] substrates
that were well controlled in terms of size and position. The growth mechanism was faceting growth without any catalyst [19].

An SEM image of GaAs grown at 700°C on poly-Si is shown in Fig. 1 (b). The underlying poly-Si substrate had been deposited at 600°C. GaAs NWs with a hexagonal pillar shape were partly obtained on poly-Si thin films (Fig. 1(c)). GaAs NWs have six-fold \{-110\} hexagonal sidewalls and grow in the \textless 111\textgreater B direction [16,17,19]. Therefore, the hexagonal sidewalls of the nanowires on the poly-Si thin films were considered to have six-fold \{-110\} oriented facets and to have grown in the \textless 111\textgreater B direction. This growth in an inclined direction probably reflects the orientations of the poly-Si grains in the mask openings.

Hillock structures that were polycrystalline islands of GaAs (Fig. 1(d)) and no growth openings (Fig. 1(e)) were also observed. SEM analysis revealed no thermal deformations or heat shrinking of the SiO$_2$ template during growth. The appearance ratio for the three types of growth morphologies (wire, hillock, and no growth) as a function of the diameter of the openings ($d_0$) are shown in Fig. 2. The highest appearance ratio for NW structures was at an opening diameter of 100 nm. The appearance ratio for hillock structures increased with the opening diameter. The appearance ratio for no growth was higher for a smaller $d_0$. These results indicate that the appearance ratio strongly depends on $d_0$. The model we propose to explain the dependency of the growth morphology on $d_0$ is as follows. When $d_0$ is small, an initial nucleus of GaAs on Si is
difficult to form because there is insufficient area for forming a stable nucleus on a Si grain in a mask opening. This is why the occurrence probabilities for both wire and hillock structures were low when $d_0$ was 100 nm or less. When $d_0$ was around 100 nm, NWs were more likely to grow because the openings were more likely to have only one Si grain, meaning that the growth was equivalent to that on a single-crystalline Si surface. When $d_0$ was larger, hillock structures, which originated from irregular growth on the grain boundary, were more likely to grow because the openings were more likely to have several Si grains. Under such conditions, nucleations occurred for more than one grain in a mask opening simultaneously. The resulting crystal nuclei interfered with each other, causing irregular polycrystalline structures to form.

To obtain more information about the formation of wire structures on poly-Si, we analyzed GaAs wire and poly-Si interface by TEM with the electron beam parallel to the (1−10) side facet of the NWs. Figure 3 shows TEM results of GaAs NWs grown at 700°C on a poly-Si substrate that had been deposited at 600°C. Figure 3 (a) shows a TEM image of a whole NW that indicates that there was lateral overgrowth of GaAs onto the SiO$_2$ masked area near the base of the grown crystal. However, the nanowires had a constant width (no tapering). Figures 3 (b) and (c) show high-resolution TEM images of the top and bottom part of the NWs showing that the nanowires grew in the [111] direction. Analysis of the selected area diffraction pattern
revealed that the bright and dark contrast corresponding to the radial direction of the NWs was due to rotational twins of the zincblende lattice in the NWs.

The results of our structural analysis clearly indicate that the GaAs NWs that formed on the poly-Si substrate had a growth mode similar to that of GaAs NWs that form on single-crystalline GaAs [18] and Si [16]. Moreover, the current NWs were inclined 6° with respect to the perpendicular direction of the substrate. This angle agrees well with the tilted angle of the crystal axis of the Si grain at the base region of the NWs (marked by the solid line in Fig. 3 (f)]. This indicates that there is a heteroepitaxial relationship between a GaAs NW and a Si grain located at the base of the NW. Furthermore, when the mask openings are mostly occupied by a single crystal grain, as shown in Fig. 3 (f), NW growth proceeds via lateral overgrowth of GaAs onto other Si grains near the base of the grown crystal. These analysis results strongly support the model of crystal growth described earlier in this section.

3.2 Grown structures dependency on growth temperature

Figure 4 (a) shows the appearance ratio of wire structures as a function of the growth temperature. The underlying poly-Si deposition temperature and mask opening diameter were 300 or 600°C and 100 nm, respectively. The highest appearance ratio for wire formation was obtained at ~700°C. This tendency is similar to the T_g dependency of the growth rate of GaAs NWs on Si(111) substrates, as shown in Fig. 4(b). These results clearly indicate that the appearance ratio of wire structures on poly-Si is correlated with the NW growth rate in the
<111>B direction. This relationship can be explained by the growth model presented below. The temperature dependence of the GaAs NW growth rate indicates that the amount of growth species migrating to the NW top surface from the side surface of the grown structures and surrounding SiO₂-masked area decreases as the temperature is increased [18]. Under high $T_G$ conditions, re-evaporation (desorption) of source materials from the surface is dominant, so the wire growth rate decreases while the wire appearance ratio decreases. Under low $T_G$ conditions, the GaAs NW growth rate is also suppressed because the effective coverage of As is high under this condition, so an As overlayer covers the As-terminated (111)B surface, resulting in the formation of stable As trimmers [24]. These trimmers prevent growth from proceeding on the (111) B surface, so the growth rate is reduced. This is the main reason few wire structure were observed on poly-Si thin layers under low $T_G$ conditions. These results for growth condition dependence indicate that the growth mechanism of GaAs nanowires on poly-Si by SA-MOVPE is attributable to the faceting-growth mechanism [19], in which the growth rate of each facet has a strong relationship with the growth conditions, including $T_G$, the same as for growth on single-crystalline GaAs and Si, for which the growth direction is also <111>B. Moreover, a growth condition that results in a higher growth rate in the <111>B direction results in an increase in the appearance ratio of wire mode growth on poly-Si.

3.3 Grown structures dependency on poly-Si deposition temperature
Finally, we grew GaAs on substrates that had been deposited at different temperatures with \( T_G \) and \( d_0 \) fixed at 760°C and 100 nm, respectively. As shown in Fig. 5, the appearance ratio of wire structures increased with \( T_S \). Since re-crystallization of Si is enhanced at higher temperature during Si deposition [25], the openings most likely had a single-crystalline surface even if the mask opening diameter was the same because the grain size of poly-Si is enlarged during the deposition of Si under higher temperature conditions. As a result, a nucleus was preferentially formed in the mask openings, which promoted stable wire growth. These results show that increasing the size of the grains by optimizing the Si deposition temperature effectively improves wire yield. This controllability of the growth mode is promising for formation of nanowires with complex structures, such as core-shell heterostructures and pn junctions, on poly-Si thin layers.

4. Summary

We investigated the SA-MOVPE growth of GaAs nanowires on poly-Si thin layers by clarifying the dependence on the growth conditions and Si deposition temperature. Our investigation of the GaAs growth morphology dependency on the mask opening diameter showed that nanowire yield correlates with the diameter of the openings and the grain size of the poly-Si. We also showed that GaAs nanowires grown on a poly-Si substrate have the same growth mechanism as
conventional GaAs nanowires grown on a GaAs substrate. The nanowire yield can be improved by adjusting the growth conditions so that the growth rate is higher in the <111>B direction. Finally, we also showed that the wire structure yield is improved by increasing the size of the grains and/or the temperature during Si deposition. The key parameters for nanowire yield are the grain size of the poly-Si layer and the growth conditions. This ability to control the growth mode is promising for the formation of nanowires with complex structures, such as core-shell heterostructures and pn junctions, on poly-Si thin layers.

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References


Figure Captions

Fig. 1  (a) Schematic illustration of growth substrate. SEM birds-eye-view images of grown substrate (b), wire structure (c), hillock structure (d), and no growth (e) for opening diameter of 100 nm and growth on poly-Si substrate at 700°C. Substrate poly-Si deposition temperature was 600°C.

Fig. 2  Appearance ratios for three types of growth morphologies against mask opening diameter. T_G and T_S were 700 and 600°C, respectively.

Fig. 3  Cross-sectional transmission electron microscopy (TEM) images of GaAs nanowire grown at 700°C on poly-Si substrate. Substrate was deposited at 600°C. Incident angle of electron beam was parallel to (1-10) side facet of GaAs nanowire. (a) Overall image of GaAs nanowire. (b) and (c) Enlarged images of open square near nanowire tip and base shown in (a), respectively. (d) and (e) High-resolution TEM images of Si grain near base of GaAs nanowire and GaAs nanowire, respectively. Insets show selected area diffraction patterns of each area obtained through fast Fourier transformation process. (f) Schematic illustration of TEM image in (c).

Fig. 4  (a) Appearance ratio of wire structures for T_S = 300 and 600°C against T_G. (b) Growth rate of nanowires on Si (111) against T_G.

Fig. 5  Appearance ratio of wire structures against T_S when T_G and d were fixed at 760°C and 100 nm, respectively.
Figure 1

(a) Diagram showing the layers of a SiO₂ Mask, Poly-Si Layer, SiO₂ Layer, Si(001) Substrate, and an Equivalent Glass Substrate.

(b) SEM image showing various features such as wires and hillocks.

(c) Close-up view of a wire labeled with [-110].

(d) Hillock indicated.

(e) No Growth indicated.
Figure 2

Appearance ratio

Opening diameter, $d_0$ (nm)

No growth

Hillock

Wire
Figure 4 (Fig4_rev.tif)

GaAs NWs on poly-Si

<table>
<thead>
<tr>
<th>Appearance ratio of wire structure (%)</th>
<th>Growth temperature, $T_G$ (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>40%</td>
<td>650</td>
</tr>
<tr>
<td>30%</td>
<td>700</td>
</tr>
<tr>
<td>20%</td>
<td>760</td>
</tr>
<tr>
<td>10%</td>
<td>$d_0 = 100$ nm, $a = 500$ nm</td>
</tr>
</tbody>
</table>

GaAs NWs on Si(111)

<table>
<thead>
<tr>
<th>Growth rate (nm/s)</th>
<th>$T_G$ (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.60</td>
<td>650</td>
</tr>
<tr>
<td>0.40</td>
<td>700</td>
</tr>
<tr>
<td>0.20</td>
<td>760</td>
</tr>
<tr>
<td>0.00</td>
<td>$d_0 = 100$ nm, $a = 500$ nm</td>
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Figure 5

- $T_G = 760 \, {}^\circ$C
- $d_0 = 100 \, \text{nm}$
- $a = 500 \, \text{nm}$

Appearance ratio of wire structure vs. Poly-Si deposition temperature, $T_S \, ({}^\circ\text{C})$.